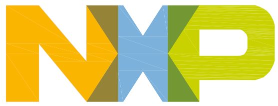

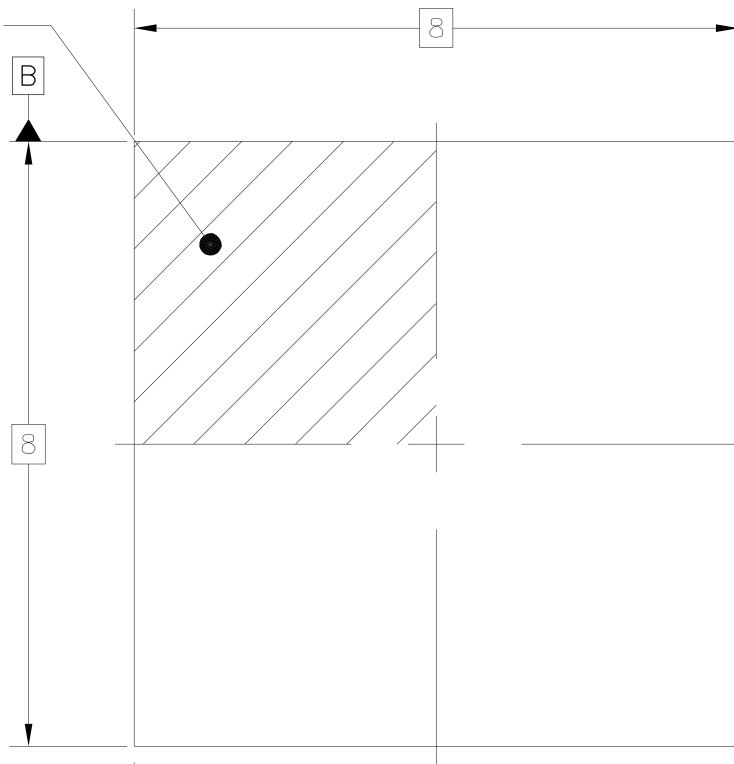

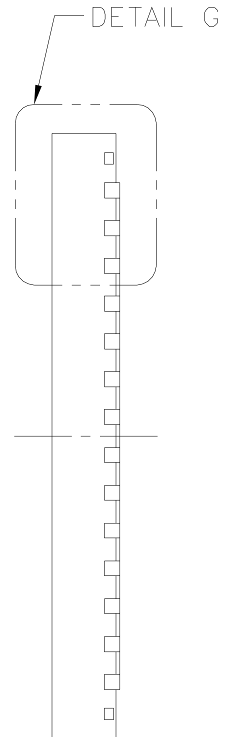

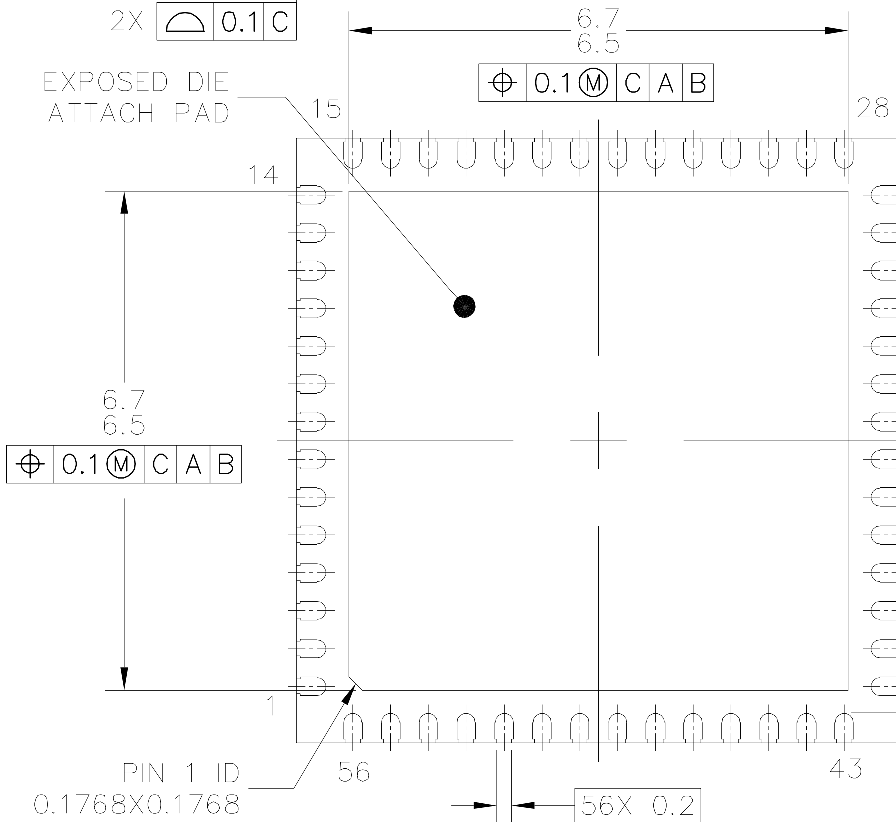

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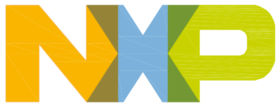
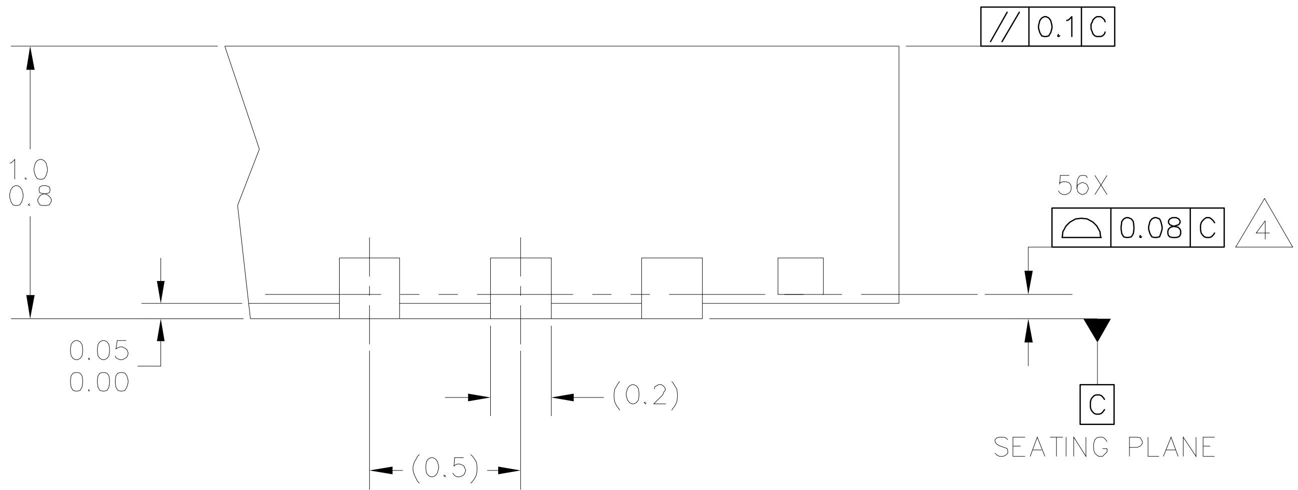
MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: QFN, THERMALLY ENHANCED, 8 X 8 X 0.9, 0.5 PITCH, 56 TERMINAL	DOCUMENT NO: 98ASA00654D REV: A
	STANDARD: NON-JEDEC
	SOT684-17 13 JAN 2016





DETAIL G
VIEW ROTATED 90°CW

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TITLE: QFN, THERMALLY ENHANCED, 8 X 8 X 0.9, 0.5 PITCH, 56 TERMINAL	DOCUMENT NO: 98ASA00654D REV: A
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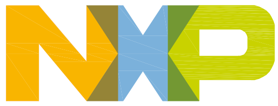

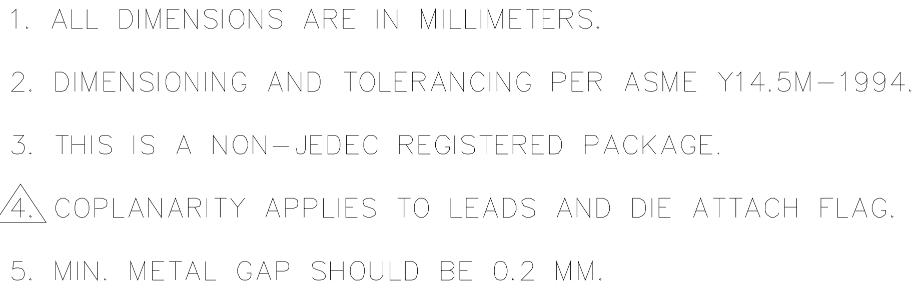

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. THIS IS A NON–JEDEC REGISTERED PACKAGE.

4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.

5. MIN. METAL GAP SHOULD BE 0.2 MM.

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

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	SOT684–17	13 JAN 2016